



- High resolution module, 20cm
- Fast conversion down to 1 ms
- Low power, 1 μA (standby < 0.15 μA)
- Integrated digital pressure sensor (24 bit ΔΣ ADC)
- Supply voltage 1.8 to 3.6 V
- Operating range: 300 to 1100 mbar, -40 to +85 °C
- Extended Pressure Range: 10 to 2000mbar
- I<sup>2</sup>C or SPI interface (Mode 0, 3)
- No external components (Internal oscillator)
- Excellent long term stability
- · Hermetically sealable for outdoor devices

## **DESCRIPTION**

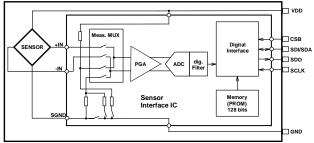
The MS5806-02BA is a new generation of high resolution altimeter sensors from MEAS Switzerland with SPI and I $^2$ C bus interface. It is optimized for altimeters and variometers with an altitude resolution of 20cm. The sensor module includes a high linearity pressure sensor and an ultra low power 24 bit  $\Delta\Sigma$  ADC with internal factory calibrated coefficients. It provides a precise digital 24 Bit pressure and temperature value and different operation modes that allow the user to optimize for conversion speed and current consumption. A high resolution temperature output allows the implementation of an altimeter/thermometer function without any additional sensor. The MS5806-02BA can be interfaced to virtually any microcontroller. The communication protocol is simple, without the need of programming internal registers in the device. The gel protection and antimagnetic stainless steel cap allows the use in 100m water resistant altimeter/compass watches. This new sensor module generation is based on leading MEMS technology and latest benefits from MEAS Switzerland proven experience and know-how in high volume manufacturing of altimeter modules, which has been widely used for over a decade. The sensing principle employed leads to very low hysteresis and high stability of both pressure and temperature signal.

## **FEATURES**

#### FIELD OF APPLICATION

- Mobile altimeter / barometer systems
- Bike computers
- Adventure or multi-mode watches
- Variometers
- Dataloggers

## **FUNCTIONAL BLOCK DIAGRAM**



**Note:** the communication protocol is defined by hardware (I2c: version 52 and SPI: version 42)

#### TECHNICAL DATA

Sensor Performances (V <sub>DD</sub> = 3 V)							
Pressure	Min	Тур	Max	Unit			
Range	10		2000	mbar			
ADC		24		bit			
Resolution (1)		/ 0.084 / .036 / 0.0		mbar			
Accuracy 25°C, 750 to 1100 mbar	-1.5		+1.5	mbar			
Accuracy -20°C to + 85°C, 300 to 1100 mbar (2)	-2.5		+2.5	mbar			
Response time		5 / 1.1 / 2 4.1 / 8.22		ms			
Long term stability		+1		mbar/yr			
Temperature	Min	Тур	Max	Unit			
Range	-40		+85	°C			
Resolution		<0.01		°C			
Accuracy at 25°C	-0.8		+0.8	°C			

Notes: (1) Oversampling Ratio: 256 / 512 / 1024 / 2048 / 4096

(2) With autozero at one pressure point

# PERFORMANCE SPECIFICATIONS

# **ABSOLUTE MAXIMUM RATINGS**

Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Supply voltage	$V_{DD}$		-0.3		+3.6	٧
Storage temperature	Ts		-40		+85	°C
Overpressure	P <sub>max</sub>	ISO 2281			10	bar
Maximum Soldering Temperature	T <sub>max</sub>	40 sec max			250	°C
ESD rating		Human Body Model	-4		+4	kV
Latch up		JEDEC standard No 78	-100		+100	mA

## **ELECTRICAL CHARACTERISTICS**

Parameter	Symbol	Conditions		Min.	Тур.	Max	Unit
Operating Supply voltage	$V_{DD}$			1.8	3.0	3.6	V
Operating Temperature	Т			-40	+25	+85	°C
-		OSR	4096		12.5		
Cupply ourrent			2048		6.3		
Supply current (1 sample per sec.)	$I_{DD}$		1024		3.2		μA
(1 Sample per Sec.)			512		1.7		
			256		0.9		
Peak supply current		during conversion			1.4		mA
Standby supply current		at 25°c			0.02	0.14	μΑ
VDD Capacitor		From VDD to	GND	100			nF

# **ANALOG DIGITAL CONVERTER (ADC)**

Parameter	Symbol	Conditions	3	Min.	Тур.	Max	Unit
Output Word					24		bit
		OSR	4096	7.40	8.22	9.04	
			2048	3.72	4.13	4.54	
Conversion time	t <sub>c</sub>		1024	1.88	2.08	2.28	ms
			512	0.95	1.06	1.17	
			256	0.48	0.54	0.60	



# PERFORMANCE SPECIFICATIONS (CONTINUED)

# PRESSURE OUTPUT CHARACTERISTICS (V<sub>DD</sub> = 3 V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Condi	tions	Min.	Тур.	Max	Unit
Operating Pressure Range	P <sub>range</sub> Full Accuracy		300		1100	mbar
Extended Pressure Range	P <sub>ext</sub>	Linear Range of ADC	10		2000	mbar
	at 25°0	C, 7001100 mbar	-1.5		+1.5	
Absolute Accuracy, no autozero	at 050	0°C, 3001100 mbar	-2.0		+2.0	mbar
	at -20.	.85°C, 3001100 mbar	-3.5		+3.5	
Absolute Acquirect, quitezere et	at 25°0	C, 7001100 mbar	-0.5		+0.5	
Absolute Accuracy, autozero at one pressure point	at 050	0°C, 3001100 mbar	-1.0		+1.0	mbar
one pressure point	at -20.	.85°C, 3001100 mbar	-2.5		+2.5	
Maximum error with supply voltage (1)	V <sub>DD</sub> = 1.8 V 3.6 V			+/- 3		mbar
Maximum error with supply voltage compensation (1) (2)	$V_{DD} = 2$	V <sub>DD</sub> = 2.2 V 3.0 V		+/-0.6		mbar
Long-term stability				+1		mbar/yr
	OSR	4096		0.024		
		2048		0.036		
Resolution RMS	1024			0.054		mbar
		512		0.084		
		256		0.130		

<sup>(1)</sup> With autozero at 3V point

# TEMPERATURE OUTPUT CHARACTERISTICS (V<sub>DD</sub> = 3 V, T = 25°C UNLESS OTHERWISE NOTED)

Parameter	Conditions		Min.	Тур.	Max	Unit
Absolute Accuracy	700 1100mbar -2085°C		-0.8 -2.0		+0.8 +2.0	°C
Maximum error with supply voltage(1)	V <sub>DD</sub> = 1.8 V 3.6 V			+/- 0.5		°C
	OSR	4096		0.002		
		2048		0.003		
Resolution RMS		1024		0.005		°C
		512		0.008		
		256		0.012		

(1) With autozero at 3V point

<sup>(2)</sup> With voltage compensation for accumulator application

# PERFORMANCE SPECIFICATIONS (CONTINUED)

# DIGITAL INPUTS (CSB, DIN, SCLK, SDA, SCL)

Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Serial data clock	SCLK	SPI protocol			10	MHz
Input high voltage	V <sub>IH</sub>	Pins CSB	80% V <sub>DD</sub>		100% V <sub>DD</sub>	V
Input low voltage	V <sub>IL</sub>		0% V <sub>DD</sub>		20% V <sub>DD</sub>	V
Input leakage current	I <sub>leak25°C</sub>	at 25°c			0.15	μA
Load capacitance	CIN			8		pF

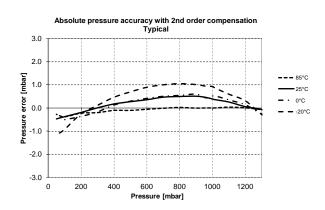
# **DIGITAL OUTPUTS (DOUT, SDA, SCL)**

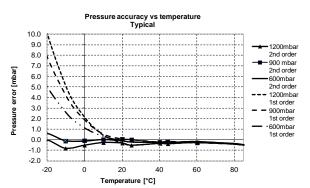
Parameter	Symbol	Conditions	Min.	Тур.	Max	Unit
Output high voltage	V <sub>OH</sub>	I <sub>source</sub> = 0.6 mA	80% V <sub>DD</sub>		100% V <sub>DD</sub>	V
Output low voltage	V <sub>OL</sub>	$I_{sink} = 0.6 \text{ mA}$	0% V <sub>DD</sub>		20% V <sub>DD</sub>	V
Load capacitance	$C_{LOAD}$			16		pF



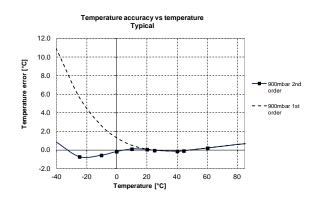
# PERFORMANCE CHARACTERISTICS

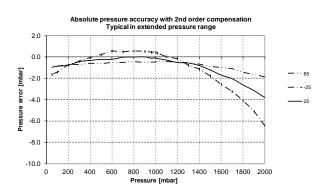
## PRESSURE ERROR VS PRESSURE AND TEMPERATURE



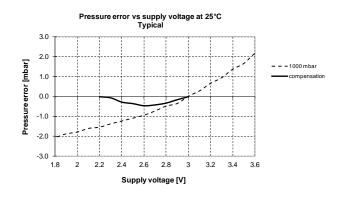


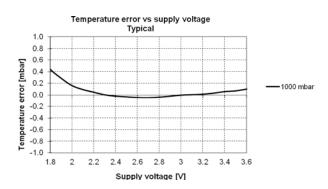
## TEMPERATURE ERROR VS TEMPERATURE AND EXTENDED PRESSURE RANGE (TYPICAL ERROR)





## PRESSURE AND PSRR TEMPERATURE VS SUPPLY VOLTAGE







## **FUNCTIONAL DESCRIPTION**

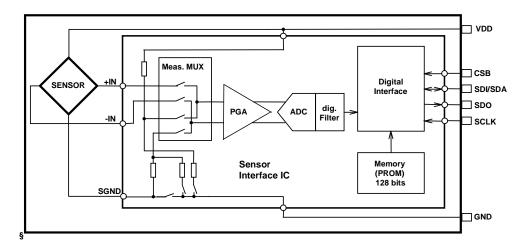


Figure 1: Block diagram of MS5806-02BA

#### **GENERAL**

The MS5806-02BA consists of a piezo-resistive sensor and a sensor interface IC. The main function of the MS5806-02BA is to convert the uncompensated analogue output voltage from the piezo-resistive pressure sensor to a 24-bit digital value, as well as providing a 24-bit digital value for the temperature of the sensor.

#### **FACTORY CALIBRATION**

Every module is individually factory calibrated at two temperatures and two pressures. As a result, 6 coefficients necessary to compensate for process variations and temperature variations are calculated and stored in the 128-bit PROM of each module. These bits (partitioned into 6 coefficients W1 to W6) must be read by the microcontroller software and used in the program converting D1 and D2 into compensated pressure and temperature values.

The 2 coefficients W0 and W7 are for factory configuration and CRC.

#### **SERIAL INTERFACE**

The MS5806-02BA has built in two types of serial interfaces: SPI and I<sup>2</sup>C. The pin PS is factory connected to GND or VCC to define the Protocol Select:

Module ref	Mode	Pins used
MS5806-02BA52	I <sup>2</sup> C	SDA, SCL, CSB
MS5806-02BA42	SPI	SDI, SDO, SCLK, CSB

#### **SPI MODE**

The external microcontroller clocks in the data through the input SCLK (Serial CLocK) and SDI (Serial Data In). In the SPI mode module can accept both mode 0 and mode 3 for the clock polarity and phase. The sensor responds on the output SDO (Serial Data Out). The pin CSB (Chip Select) is used to enable/disable the interface, so that other devices can talk on the same SPI bus. The CSB pin can be pulled high after the command is sent or after the end of the command execution (for example end of conversion). The best noise performance from the module is obtained when the SPI bus is quiet and without communication to other devices during the ADC conversion in progress.

# I<sup>2</sup>C MODE

The external microcontroller clocks in the data through the input SCLK (Serial CLocK) and SDA (Serial DAta). The sensor responds on the same pin SDA which is bidirectional for the I<sup>2</sup>C bus interface. So this interface type uses only 2 signal lines and does not require a chip select, which can be favorable to reduce board space. In I<sup>2</sup>C-Mode the complement of the pin CSB (Chip Select) represents the LSB of the I<sup>2</sup>C address. It is possible to use two sensors with two different addresses on the I<sup>2</sup>C bus. The pin CSB shall be connected to VDD or GND (do not leave unconnected!).

Pin CSB	Address (7 bits)
High	0x76 (1110110 b)
Low	0x77 (1110111 b)

#### **COMMANDS**

The MS5806-02BA has only five basic commands:

- 1. Reset
- 2. Read PROM (128 bit of calibration words)
- 3. D1 conversion
- 4. D2 conversion
- 5. Read ADC result (24 bit pressure / temperature)

	Comma	and by	te						hex value
Bit number	0	1	2	3	4	5	6	7	
Bit name	PRM	COV	-	Тур	Ad2/ Os2	Ad1/ Os1	Ad0/ Os0	Stop	
Command									
Reset	0	0	0	1	1	1	1	0	0x1E
Convert D1 (OSR=256)	0	1	0	0	0	0	0	0	0x40
Convert D1 (OSR=512)	0	1	0	0	0	0	1	0	0x42
Convert D1 (OSR=1024)	0	1	0	0	0	1	0	0	0x44
Convert D1 (OSR=2048)	0	1	0	0	0	1	1	0	0x46
Convert D1 (OSR=4096)	0	1	0	0	1	0	0	0	0x48
Convert D2 (OSR=256)	0	1	0	1	0	0	0	0	0x50
Convert D2 (OSR=512)	0	1	0	1	0	0	1	0	0x52
Convert D2 (OSR=1024)	0	1	0	1	0	1	0	0	0x54
Convert D2 (OSR=2048)	0	1	0	1	0	1	1	0	0x56
Convert D2 (OSR=4096)	0	1	0	1	1	0	0	0	0x58
ADC Read	0	0	0	0	0	0	0	0	0x00
PROM Read	1	0	1	0	Ad2	Ad1	Ad0	0	0xA0 to 0xAE

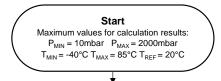
Figure 2: Command structure

PRM	PROM read bit					
COV	Conversion selection bit					
Тур	D1 or D2 selection bit (Conversion mode)					
ADx / OSx Address PROM or OSR configuration						
Stop Stop bit						

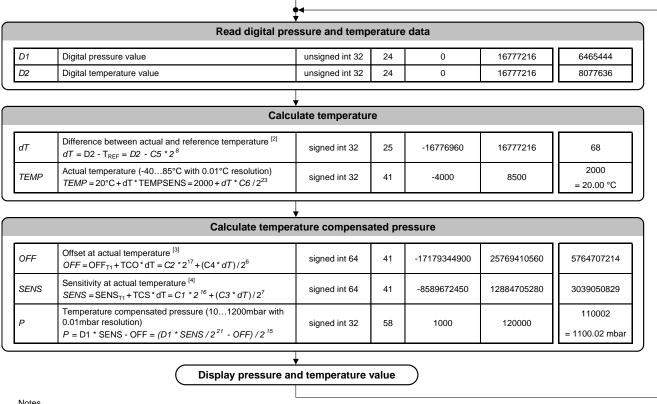
Figure 2a: Bit description



# PRESSURE AND TEMPERATURE CALCULATION



Variable	Description   Equation	Recommended variable type	Size [1]	Val	Example /	
			[bit]	min	max	Typical
C1	Pressure sensitivity   SENS <sub>T1</sub>	unsigned int 16	16	0	65535	46372
C2	Pressure offset   OFF <sub>T1</sub>	unsigned int 16	16	0	65535	43981
СЗ	Temperature coefficient of pressure sensitivity   TCS	unsigned int 16	16	0	65535	29059
C4	Temperature coefficient of pressure offset   TCO	unsigned int 16	16	0	65535	27842
C5	Reference temperature   T <sub>REF</sub>	unsigned int 16	16	0	65535	31553
C6	Temperature coefficient of the temperature   TEMPSENS	unsigned int 16	16	0	65535	28165



Notes

[1] Maximal size of intermediate result during evaluation of variable

min and max have to be defined [2]

[3] min and max have to be defined

min and max have to be defined

Figure 3: Flow chart for pressure and temperature reading and software compensation.



#### SECOND ORDER TEMPERATURE COMPENSATION

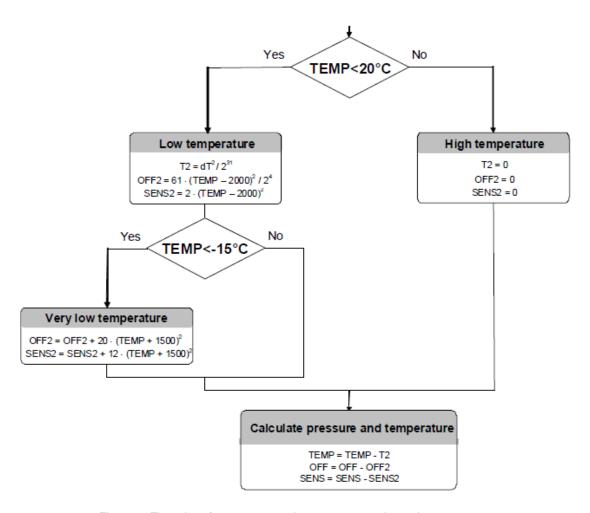


Figure 4: Flow chart for pressure and temperature to the optimum accuracy.

## PRESSURE COMPENSATION WITH SUPPLY VOLTAGE

It is recommended to use this formula only in the specified voltage range. During the ADC conversion, the power supply  $V_{\text{DD}}$  must be stable.

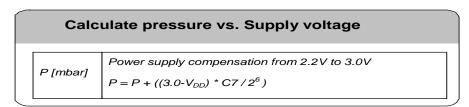


Figure 5: Flow chart for pressure compensation VS supply voltage.



# SPI INTERFACE (MS5806-02BA42 ONLY)

# **RESET SEQUENCE**

The Reset sequence shall be sent once after power-on to make sure that the calibration PROM gets loaded into the internal register. It can be also used to reset the device ROM from an unknown condition

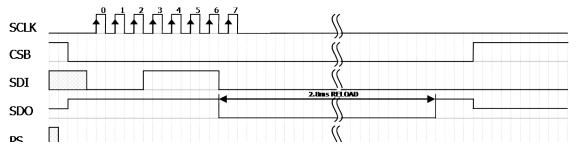


Figure 6: Reset command sequence SPI mode 0

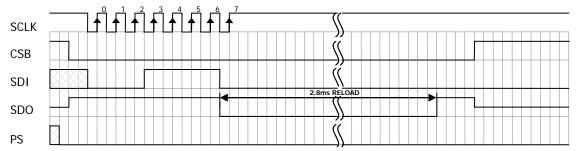


Figure 6a: Reset command sequence SPI mode 3

#### **CONVERSION SEQUENCE**

The conversion command is used to initiate uncompensated pressure (D1) or uncompensated temperature (D2) conversion. The chip select can be disabled during this time to communicate with other devices.

After the conversion, using ADC read command the result is clocked out with the MSB first. If the conversion is not executed before the ADC read command, or the ADC read command is repeated, it will give 0 as the output result. If the ADC read command is sent during conversion the result will be 0, the conversion will not stop and the final result will be wrong. Conversion sequence sent during the already started conversion process will yield incorrect result as well.

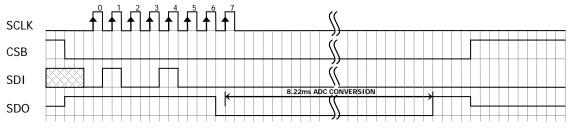


Figure 7: Conversion out sequence, Typ=d1, OSR = 4096

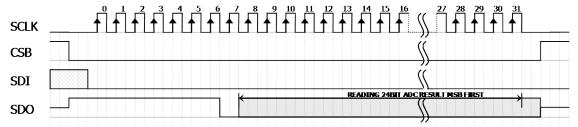


Figure 8: ADC Read sequence

#### **PROM READ SEQUENCE**

The read command for PROM shall be executed once after reset by the user to read the content of the calibration PROM and to calculate the calibration coefficients. There are in total 8 addresses resulting in a total memory of 128 bit. Address 0 contains factory data and the setup, addresses 1-6 calibration coefficients and address 7 contains the serial code and CRC. The command sequence is 8 bits long with a 16 bit result which is clocked with the MSB first.

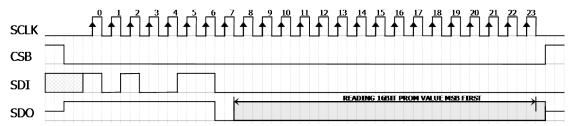


Figure 9: PROM Read sequence, address = 011 (Coefficient 3)



# I<sup>2</sup>C INTERFACE (MS5806-02BA52 ONLY)

#### **COMMANDS**

Each I<sup>2</sup>C communication message starts with the start condition and it is ended with the stop condition. The MS5806-02BA address is 111011Cx, where C is the complementary value of the pin CSB. Since the IC does not have a microcontroller inside, the commands for I<sup>2</sup>C and SPI are quite similar.

#### **RESET SEQUENCE**

The reset can be sent at any time except when the power on did not work it could be possible that the acknowledge blocks the SDA. When SDA is blocked by an undefined state the only way to get the MS5806-02BA to work is to send a power on reset.

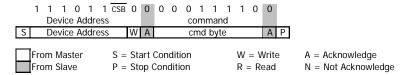


Figure 10: I<sup>2</sup>C Reset Command

#### **CONVERSION SEQUENCE**

A conversion can be started by sending the command to MS5806-02BA. When command is sent to the system it stays busy until conversion is done. When conversion is finished the data can be accessed by sending a Read command, when an acknowledge appears from the MS5806-02BA, you may then send 24 SCLK cycles to get all result bits. Every 8 bit the system waits for an acknowledge signal.

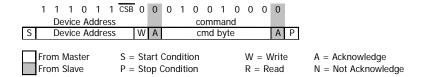


Figure 11: I<sup>2</sup>C Command to initiate a pressure conversion (OSR=4096, typ=D1)

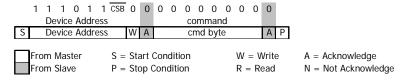


Figure 12: I<sup>2</sup>C ADC read sequence



Figure 13: I<sup>2</sup>C pressure response (D1) on 24 bit from MS5806-02BA

#### **PROM READ SEQUENCE**

The PROM Read command consists of two parts. First command sets up the system into PROM read mode. The second part gets the data from the system.

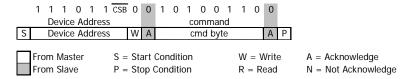


Figure 14: I<sup>2</sup>C Command to read memory address= 011 (Coefficient 3)

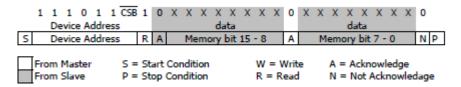


Figure 15: I<sup>2</sup>C answer from MS5806-02BA

# **CYCLIC REDUNDANCY CHECK (CRC)**

MS5806-02BA contains a PROM memory with 128-Bit. A 4-bit CRC has been implemented to check the data validity in memory. The application note AN520 describes in detail CRC-4 code used.

A d d	D B 1 5	D B 1	D B 1 3	D B 1 2	D B 1	D B 1 0	D B 9	D B 8	D B 7	D B 6	D B 5	D B 4	D B 3	D B 2	D B 1	D B 0
0	16 bit reserved for manufacturer															
1	Coefficient 1 (16 bit unsigned)															
2	Coefficient 2 (16 bit unsigned)															
3	Coefficient 3 (16 bit unsigned)															
4	Coefficient 4 (16 bit unsigned)															
5	Coefficient 5 (16 bit unsigned)															
6	Coefficient 6 (16 bit unsigned)															
7	Coefficient 7 (8 bit unsigned)															

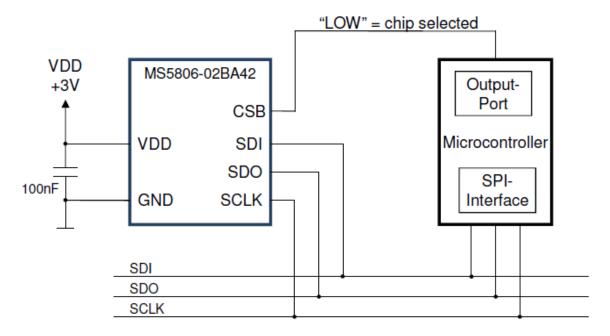
Figure 16: Memory PROM mapping



# **APPLICATION CIRCUIT**

The MS5806-02BA is a circuit that can be used in conjunction with a microcontroller in mobile altimeter applications. It is designed for low-voltage systems with a supply voltage of 3 V.

# **SPI** protocol communication



# **I2C** protocol communication

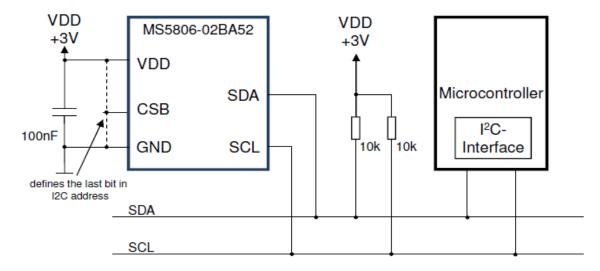


Figure 17: Typical application circuit with SPI / I<sup>2</sup>C protocol communication



February 25<sup>th</sup>, 2014

# PIN CONFIGURATION AND DEVICE PACKAGE OUTLINE

SPECIFIED DIM ARE IN MILLIMETERS LINEAR DIMENSIONS  $\pm\,0.1$ 

NOTE: 1: CAP CENTERING  $\pm 0.15$  FROM THE CENTRE OF CERAMIC

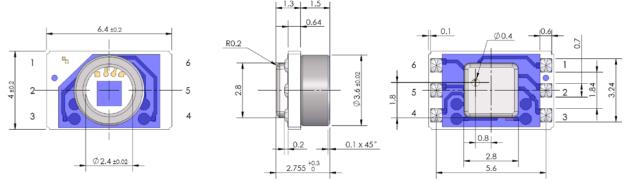


Figure 18: Pin configuration and package outlines, recommended PCB footprint

PIN	NAME: I2C - SPI	TYPE	FUNCTION
1	SDI – SDA	I	Serial Data Input
2	CSB		Chip Select (Active low)
3	VDD	Р	Positive Supply Voltage
4	GND	G	Ground
5	SCLK – SCL	I	Serial Data Clock
6	SDO - NU	0	Serial Data Out

# RECOMMENDED PAD LAYOUT

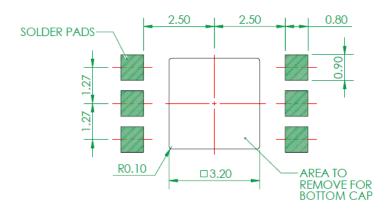
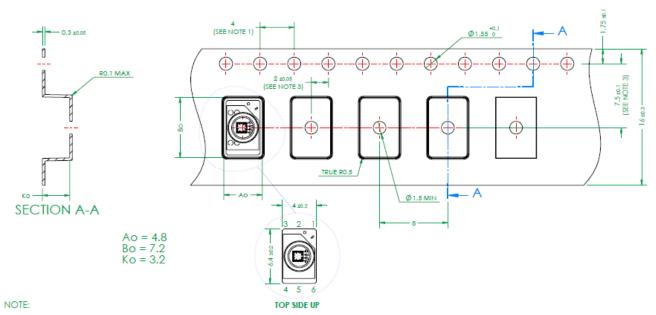


Figure 19: Pin configuration and package outlines, recommended PCB footprint



# **SHIPPING PACKAGE**



- 1: 10 SPROCKET HOLE PITCH CUMULATIVE TOLERANCE ±0.2
   2: CAMBER IN COMPLIANCE WITH EIA 481
   3: POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITIONOF POCKET, NOT POCKET HOLE

Figure 20: Tape & reel

# measurement S P E C I A L T I E S<sup>TM</sup>

# MS5806-02BA Miniature Altimeter Module

## MOUNTING AND ASSEMBLY CONSIDERATIONS

#### **SOLDERING**

Please refer to the application note AN808 available on our website for all soldering issues.

#### **MOUNTING**

The MS5806-02BA can be placed with automatic Pick & Place equipment using vacuum nozzles. It will not be damaged by the vacuum. Due to the low stress assembly the sensor does not show pressure hysteresis effects. It is important to solder all contact pads.

#### **CONNECTION TO PCB**

The package outline of the module allows the use of a flexible PCB for interconnection. This can be important for applications in watches and other special devices.

#### **SEALING WITH O-RINGS**

In products like outdoor watches the electronics must be protected against direct water or humidity. For those products the MS5806-02BA provides the possibility to seal with an O-ring. The protective cap of the MS5806-02BA is made of special anticorrosive stainless steel with a polished surface. In addition to this the MS5806-02BA is filled with silicone gel covering the sensor and the bonding wires. The O-ring (or O-rings) shall be placed at the outer diameter of the metal cap. This method avoids mechanical stress because the sensor can move in vertical direction.

#### **CLEANING**

The MS5806-02BA has been manufactured under cleanroom conditions. It is therefore recommended to assemble the sensor under class 10'000 or better conditions. Should this not be possible, it is recommended to protect the sensor opening during assembly from entering particles and dust. To avoid cleaning of the PCB, solder paste of type "no-clean" shall be used. Cleaning might damage the sensor!

# **ESD PRECAUTIONS**

The electrical contact pads are protected against ESD up to 4 kV HBM (human body model). It is therefore essential to ground machines and personnel properly during assembly and handling of the device. The MS5806-02BA is shipped in antistatic transport boxes. Any test adapters or production transport boxes used during the assembly of the sensor shall be of an equivalent antistatic material.

## **DECOUPLING CAPACITOR**

Particular care must be taken when connecting the device to the power supply. A 100 nF ceramic capacitor must be placed as close as possible to the MS5806-02BA VDD pin. This capacitor will stabilize the power supply during data conversion and thus, provide the highest possible accuracy.



## ORDERING INFORMATION

Product Code	Product	Art. No	Delivery Form
MS5806-02BA52	MS5806-02BA I2C Miniature Altimeter Module	MS580602BA52-51	Tape& reel TOP-UP
MS5806-02BA42	MS5806-02BA SPI Miniature Altimeter Module	MS580602BA42-51	Tape& reel TOP-UP

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